

MS23P25 P-Channel 20-V (D-S) MOSFET

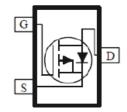
GENERAL DESCRIPTION

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low RDS(on) and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, and PCMCIA cards, cellular and cordless telephones.

FEATURES

- ·Low rDS(on)provides higher efficiency and extends battery life
- •Low thermal impedance copper leadframe SOT-23 saves board space
- ·Fast switching speed
- ·High performance trench technology





1.Gate 2. Drain 3. Source RoHS
COMPLIANT

FREE Avaliable

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)							
Parameter	Symbol	Value	Unit				
Drain-Source Voltage	VDS	-20	V				
Gate-Source Voltage	VGS	±12	V				
Continuous Drain Current @ TC=25°C	ID	-3.6	A				
Pulsed Drain Current	IDM	-10	A				
Continuous Source Current (Diode Conduction)	IS	0.46	A				
Operating Junction and Storage Temperature	Tj, Tstg	-55~+150	°C				
Power Dissipation@ TC=25°C	Pd	1.25	W				

NOTE:

1. Repetitive rating; pulse width limited by maximum junction temperature.

Thermal characteristics (Tc=25°C unless otherwise noted)							
Parameter	Symbol	Value	Unit				
Maximum Junction-to-Ambient	RθJA	100					
Maximum Junction-to-Case	RθJc	106	°C/W				



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SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)								
Parameter	Sambal	Test Conditions	Limits			TI24		
	Symbol		Min	Тур	Max	Unit		
Static								
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \text{ uA}$	-0.7					
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			±100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	uA		
	1055	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			-10	uA		
On-State Drain Current ^A	$I_{D(on)}$	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-10			A		
Drain-Source On-Resistance ^A		$V_{GS} = -4.5 \text{ V}, I_D = -3.6 \text{ A}$			55	mΩ		
	$r_{DS(on)}$	$V_{GS} = -2.5 \text{ V}, I_D = -2.8 \text{ A}$			89			
		$V_{GS} = -1.8 \text{ V}, I_D = -1.8 \text{ A}$			200			
Forward Tranconductance ^A	g_{fs}	$V_{DS} = -5 \text{ V}, I_D = -3.6 \text{ A}$		12		S		
Diode Forward Voltage	V_{SD}	$I_S = -0.46 \text{ A}, V_{GS} = 0 \text{ V}$		-0.60		V		
Dynamic ^b			•		•	•		
Total Gate Charge	Qg	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V},$ $I_{D} = -3.6 \text{ A}$		16.7		пC		
Gate-Source Charge	Qgs			1.8				
Gate-Drain Charge	Q_{gd}	ID3.0 A		1.9				
Turn-On Delay Time	$t_{d(on)}$			9		ns		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, I_L = -1 \text{ A},$ $V_{GEN} = -4.5 \text{ V}, R_G = 6 \Omega$		4				
Turn-Off Delay Time	t _{d(off)}			25				
Fall-Time	t _f			20		[

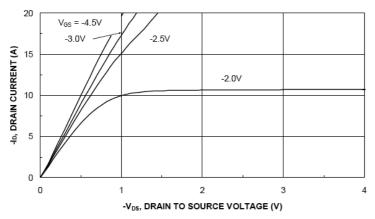
Notes

- a. Pulse test: PW \leq 300us duty cycle \leq 2%.
- b. Guaranteed by design, not subject to production testing.
- c. Repetitive rating, pulse width limited by junction temperature.



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Typical Electrical Characteristics



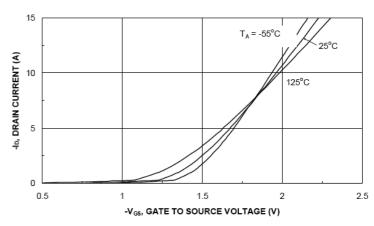
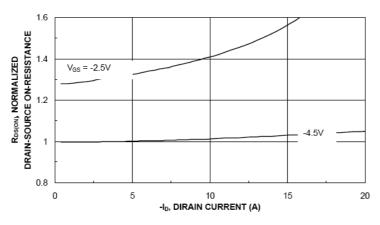


Figure 1. Output Characteristics

Figure 2. Transfer Characteristics



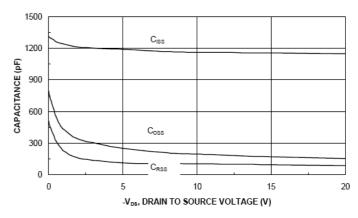
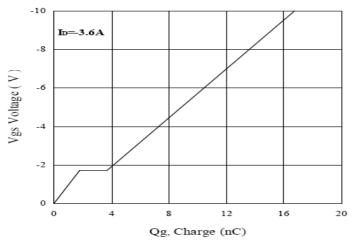


Figure 3. On-Resistance vs. Drain Current

Figure 4. Capacitance



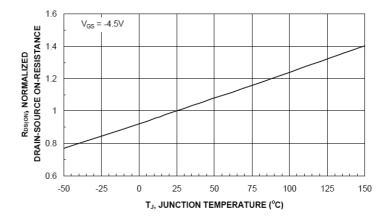


Figure 5. Gate Charge

Figure 6. On-Resistance vs. Junction Temperature